

Title (en)

COMPONENT ARRANGEMENT, PACKAGE AND PACKAGE ARRANGEMENT, AS WELL AS PRODUCTION METHOD

Title (de)

BAUTEILANORDNUNG, PACKAGE UND PACKAGE-ANORDNUNG SOWIE VERFAHREN ZUM HERSTELLEN

Title (fr)

ENSEMBLE DE COMPOSANT, EMBALLAGE ET ENSEMBLE D'EMBALLAGE AINSI QUE PROCÉDÉ DE FABRICATION

Publication

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Application

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Abstract (en)

[origin: WO2019154465A1] The invention relates to a component arrangement, comprising a carrier substrate (1); a spacer (3) which is arranged on the carrier substrate surrounding an installation space (1a) and has an outlet opening on a side facing away from the carrier substrate; an optical component (2) arranged in the installation space; a contact connection which electrically conductively connects the optical component to external contacts arranged outside the installation space; a cover substrate (4) which is arranged on the spacer and with which the outlet opening is covered in a light-permeable manner; and a light-reflecting surface (6) which forms an anisotropically etched silicon component and is arranged in the installation space as an inclined surface at an angle of approx. 45° relative to the surface of the carrier substrate facing the installation space, in such a way that light radiating in a horizontal direction onto the light-reflecting surface can be radiated out in the vertical direction through the opening and the cover substrate, and vice versa. The invention also relates to a method for producing a component arrangement, as well as a package, a package arrangement and a production method.

IPC 8 full level

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